



Data Sheet

September 2013 File Number 2253.2

N-Channel Power MOSFET 50V, 30A, 40 mΩ

This is an N-Channel enhancement mode silicon gate power field effect transistor designed for applications such as switching regulators, switching converters, motor drivers, relay drivers and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. This type can be operated directly from integrated circuits.

Formerly developmental type TA9771.

Ordering Information

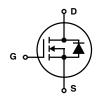
PART NUMBER	PACKAGE	BRAND		
BUZ11_NR4941	TO-220AB	BUZ11		

NOTE: When ordering, use the entire part number.

Features

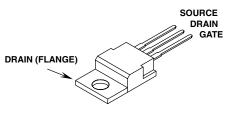
- 30A, 50V
- r_{DS(ON)} = 0.040Ω
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- · Linear Transfer Characteristics
- High Input Impedance
- Majority Carrier Device
- Related Literature
 - TB334 "Guidelines for Soldering Surface Mount Components to PC Boards"

Symbol



Packaging

JEDEC TO-220AB



Absolute Maximum Ratings $T_C = 25^{\circ}C$, Unless Otherwise Specified

	BUZ11	UNITS
Drain to Source Breakdown Voltage (Note 1)V _{DS}	50	V
Drain to Gate Voltage (R _{GS} = 20kΩ) (Note 1) V _{DGR}	50	V
Continuous Drain Current $T_C = 30^{\circ}CI_D$	30	Α
Pulsed Drain Current (Note 3)	120	А
Gate to Source VoltageV _{GS}	±20	V
Maximum Power Dissipation	75	W
Linear Derating Factor	0.6	W/ ^o C
Operating and Storage Temperature	-55 to 150	°C
DIN Humidity Category - DIN 40040	E	
IEC Climatic Category - DIN IEC 68-1	55/150/56	
Maximum Temperature for Soldering		_
Leads at 0.063in (1.6mm) from Case for 10sTL	300	°C
Package Body for 10s, See Techbrief 334	260	°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}C$ to $125^{\circ}C$.

Electrical Specifications T_C

 $T_C = 25^{\circ}C$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	ТҮР	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	$I_{D} = 250 \mu A, V_{GS} = 0V$	50	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 1mA$ (Figure 9)	2.1	3	4	V
Zero Gate Voltage Drain Current	IDSS	$T_J = 25^{o}C, V_{DS} = 50V, V_{GS} = 0V$	-	20	250	μA
		$T_{J} = 125^{o}C, V_{DS} = 50V, V_{GS} = 0V$	-	100	1000	μA
Gate to Source Leakage Current	IGSS	$V_{GS} = 20V, V_{DS} = 0V$	-	10	100	nA
Drain to Source On Resistance (Note 2)	rDS(ON)	I _D = 15A, V _{GS} = 10V (Figure 8)	-	0.03	0.04	Ω
Forward Transconductance (Note 2)	9fs	V _{DS} = 25V, I _D = 15A (Figure 11)	4	8	-	S
Turn-On Delay Time	t _{d(ON)}	V_{CC} = 30V, I_D \approx 3A, V_{GS} = 10V, R_{GS} = 50 $\Omega,$ R_L = 10 Ω	-	30	45	ns
Rise Time	t _r		-	70	110	ns
Turn-Off Delay Time	t _{d(OFF)}		-	180	230	ns
Fall Time	t _f		-	130	170	ns
Input Capacitance	C _{ISS}	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$ (Figure 10)	-	1500	2000	pF
Output Capacitance	C _{OSS}		-	750	1100	pF
Reverse Transfer Capacitance	C _{RSS}		-	250	400	pF
Thermal Resistance Junction to Case	R _{0JC}			≤ 1.67		°C/W
Thermal Resistance Junction to Ambient	R _{0JA}			≤ 75		°C/W

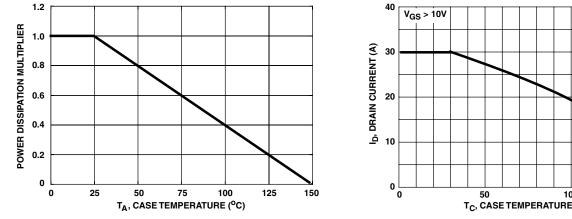
Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	ТҮР	MAX	UNITS
Continuous Source to Drain Current	I _{SD}	$T_{C} = 25^{\circ}C$	-	-	30	Α
Pulsed Source to Drain Current	I _{SDM}	$T_{C} = 25^{\circ}C$	-	-	120	А
Source to Drain Diode Voltage	V _{SD}	$T_{J} = 25^{\circ}C, I_{SD} = 60A, V_{GS} = 0V$	-	1.7	2.6	V
Reverse Recovery Time	t _{rr}	$T_J = 25^{o}C$, $I_{SD} = 30A$, $dI_{SD}/dt = 100A/\mu s$,	-	200	-	ns
Reverse Recovery Charge	Q _{RR}	$V_{R} = 30V$	-	0.25	-	μC

NOTES:

2. Pulse Test: Pulse width \leq 300ms, duty cycle \leq 2%.

3. Repetitive rating: pulse width limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3).



Typical Performance Curves Unless Otherwise Specified



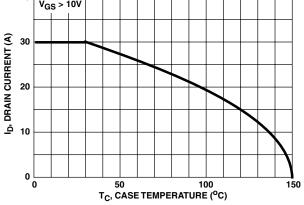
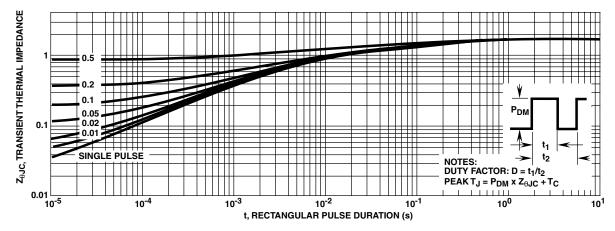


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs **CASE TEMPERATURE**





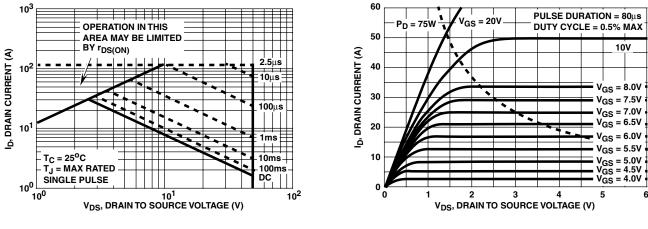
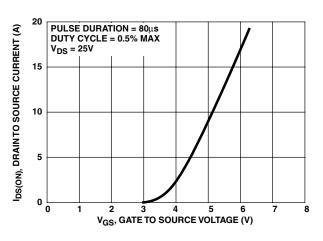


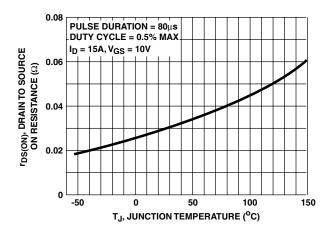
FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

FIGURE 5. OUTPUT CHARACTERISTICS



Typical Performance Curves Unless Otherwise Specified (Continued)







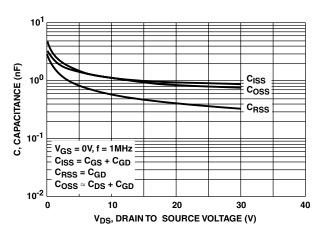


FIGURE 10. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

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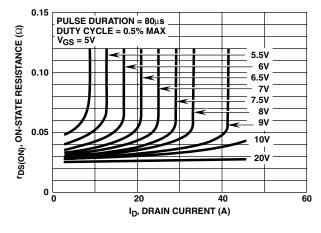


FIGURE 7. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

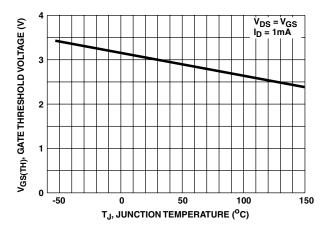
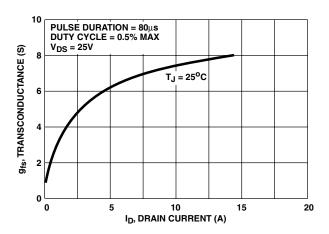
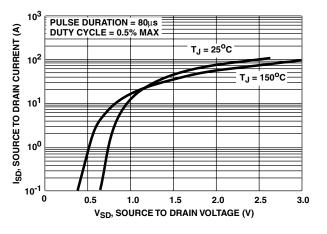


FIGURE 9. GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE





BUZ11 Rev. C0



Typical Performance Curves Unless Otherwise Specified (Continued)

FIGURE 12. SOURCE TO DRAIN DIODE VOLTAGE

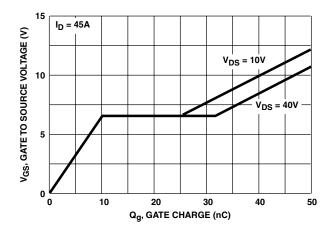


FIGURE 13. GATE TO SOURCE VOLTAGE vs GATE CHARGE

Test Circuits and Waveforms

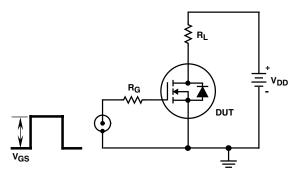


FIGURE 14. SWITCHING TIME TEST CIRCUIT

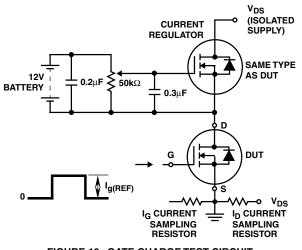


FIGURE 16. GATE CHARGE TEST CIRCUIT

t_{ON} tOFF td(ON) d(OFF t, tf V_{DS} 90% 90% 10% 10% 0 90% VGS 50% 50% 0 10% PULSE WIDTH

FIGURE 15. RESISTIVE SWITCHING WAVEFORMS

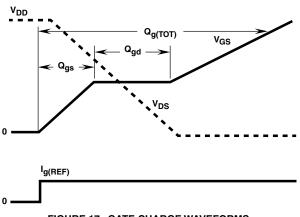


FIGURE 17. GATE CHARGE WAVEFORMS



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